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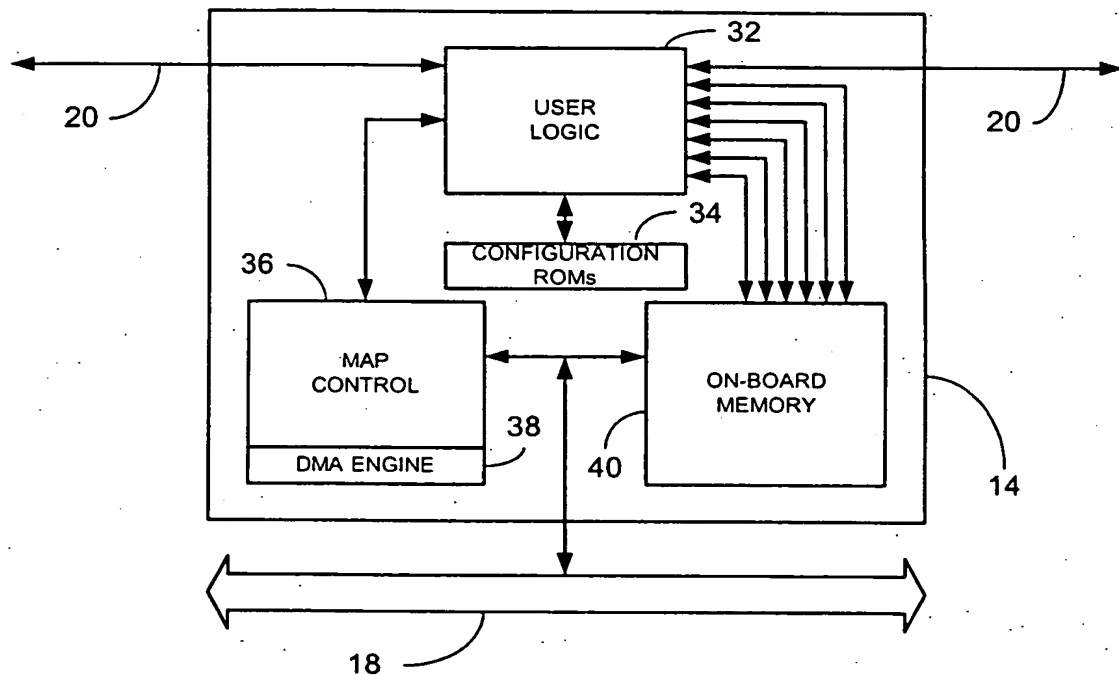
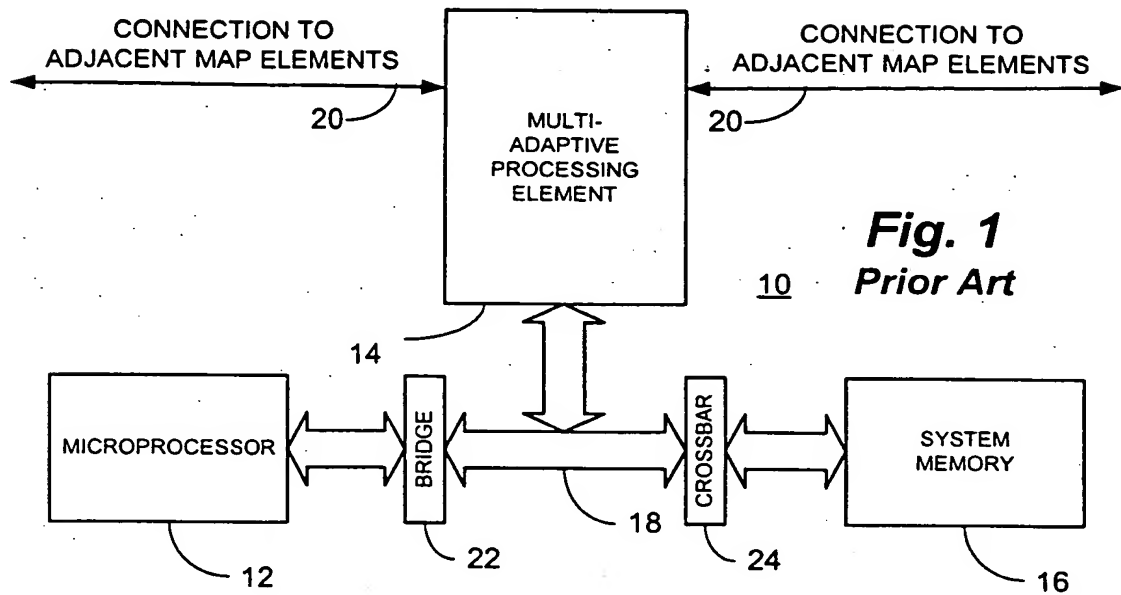
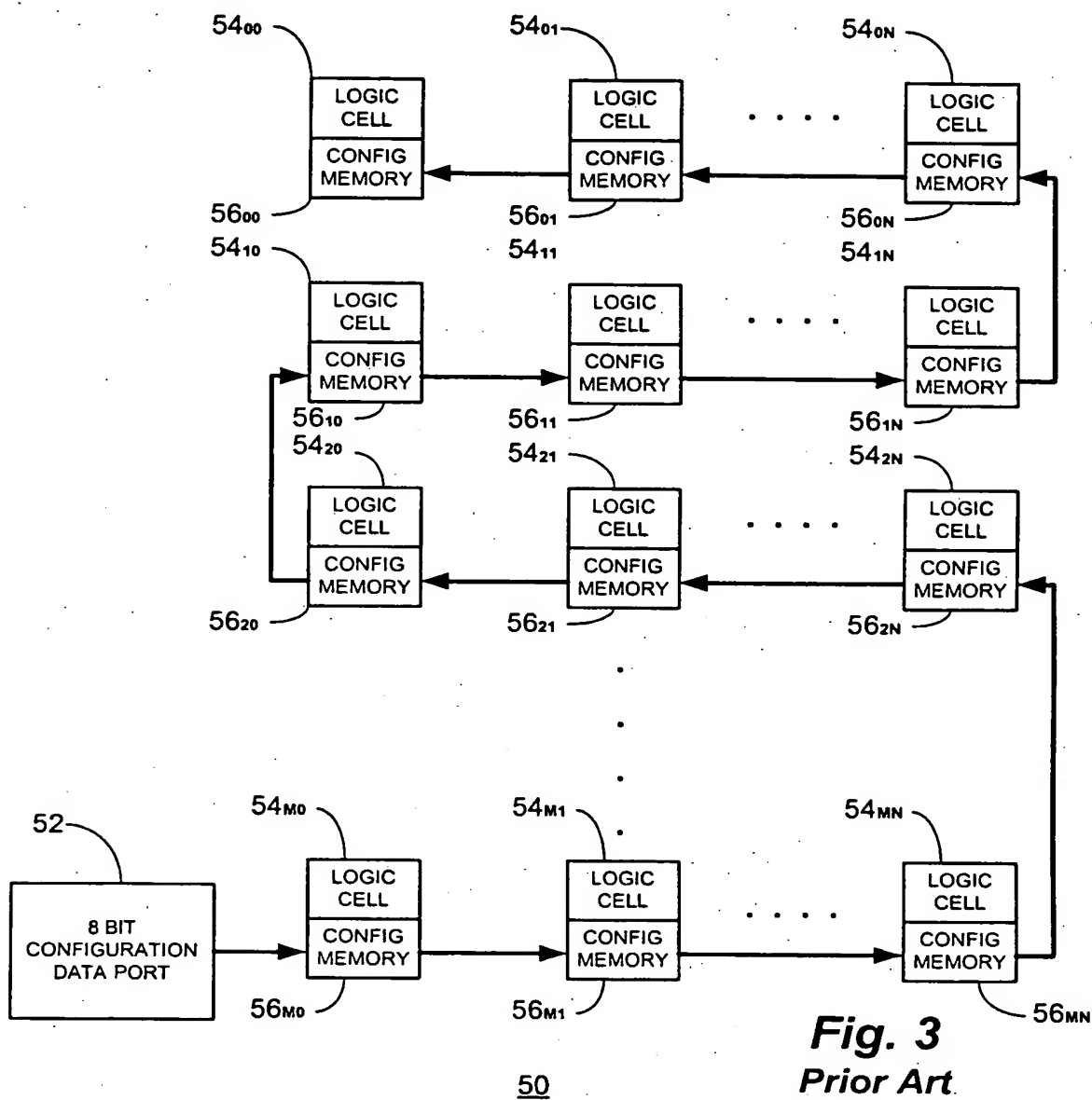


Fig. 2
Prior Art

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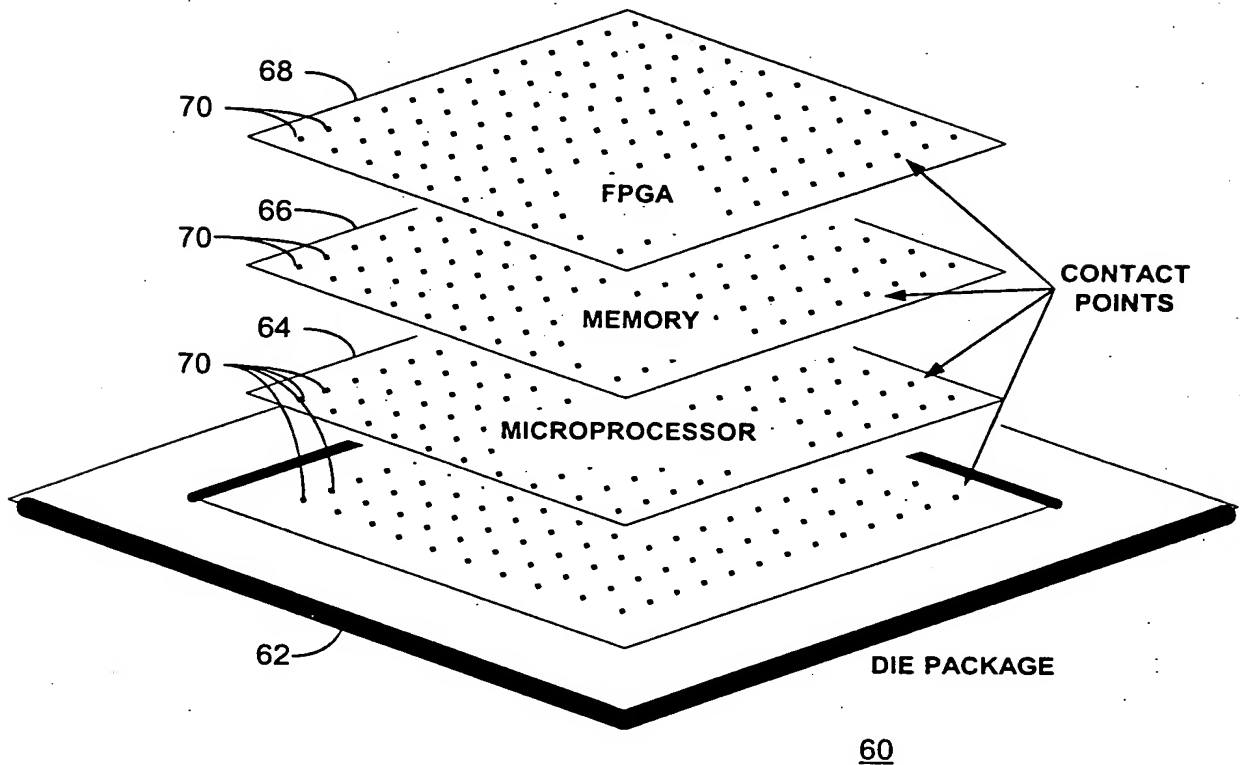


Fig. 4

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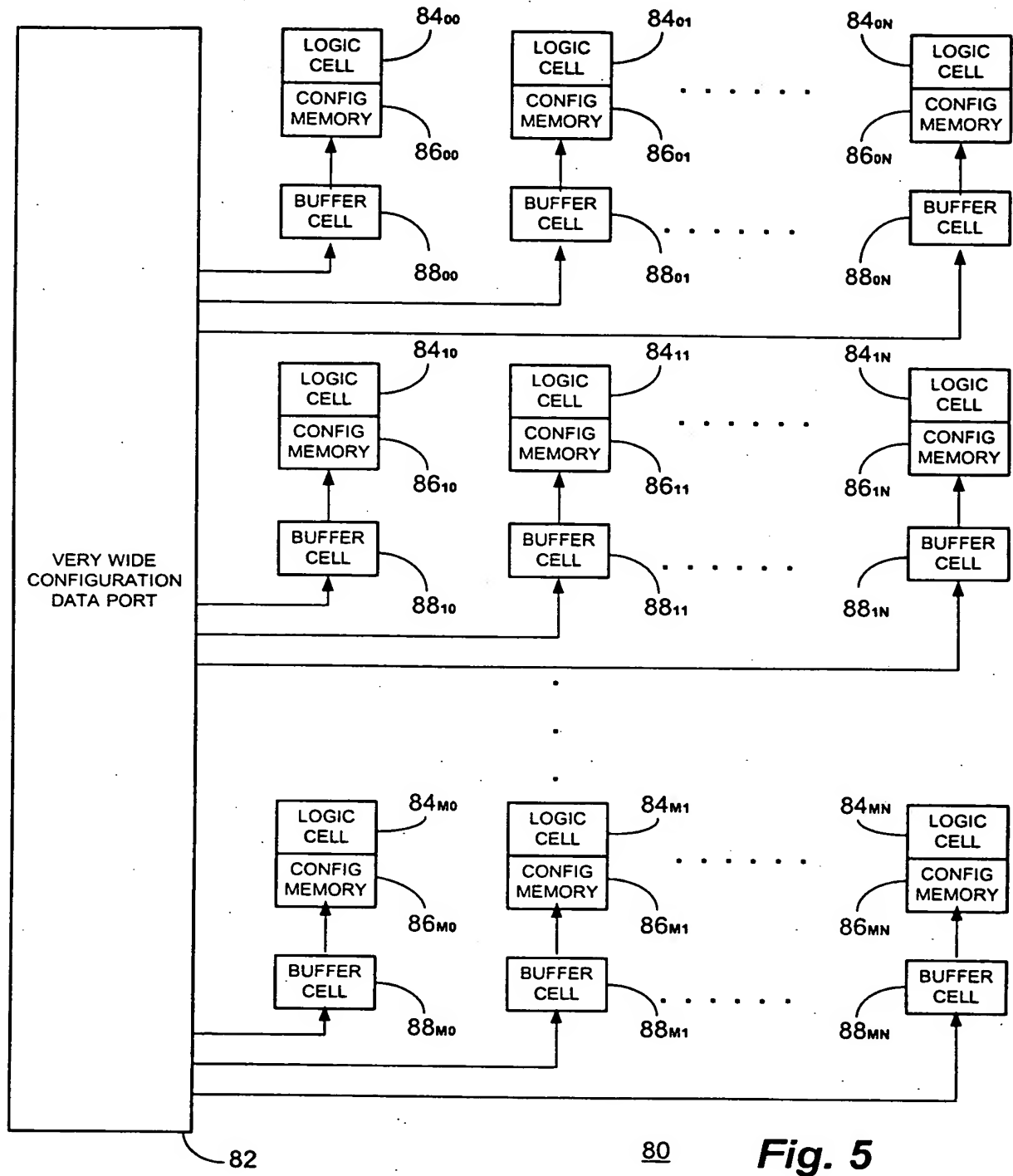


Fig. 5

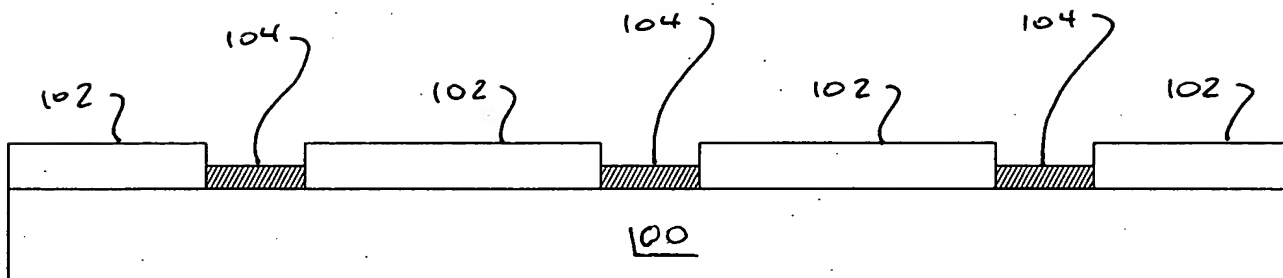


FIG. 6

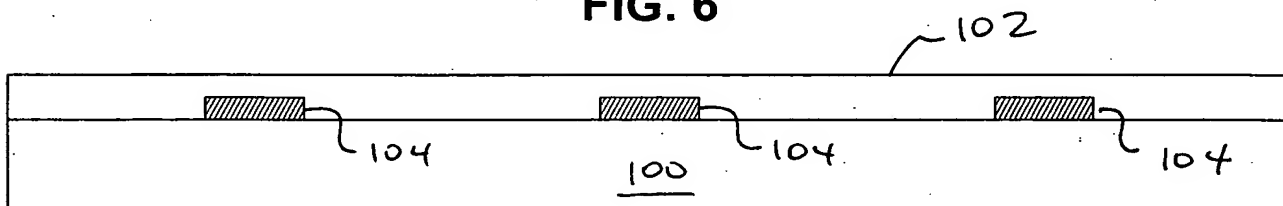


FIG. 7

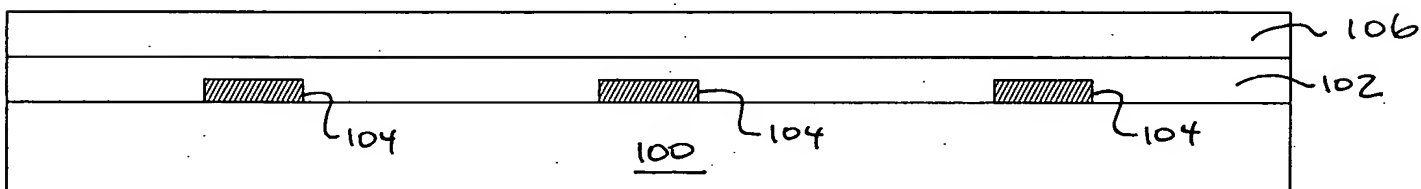


FIG. 8

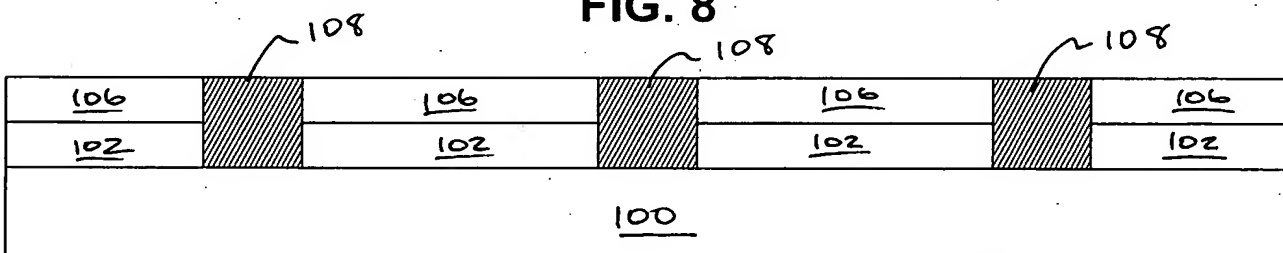


FIG. 9

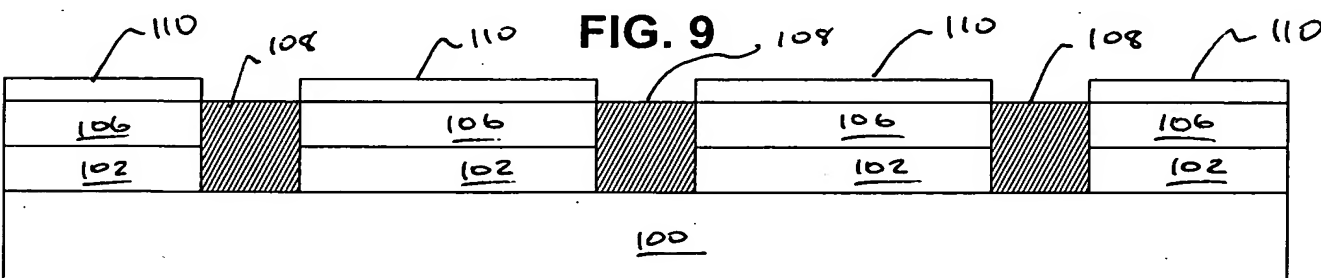


FIG. 10

S/N: -----
Docket No.: ARB001 CONCIP
Title: RECONFIGURABLE PROCESSOR MODULE
COMPRISING HYBRID STACKED INTEGRATED
CIRCUIT DIE ELEMENTS
Inv: Jon M. Huppenthal & D. James Guzy

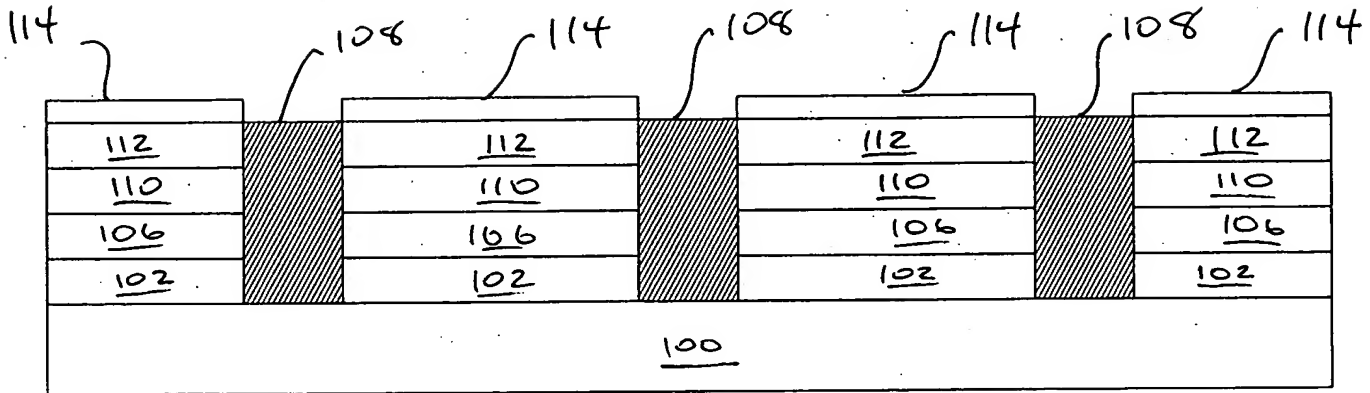


FIG. 11